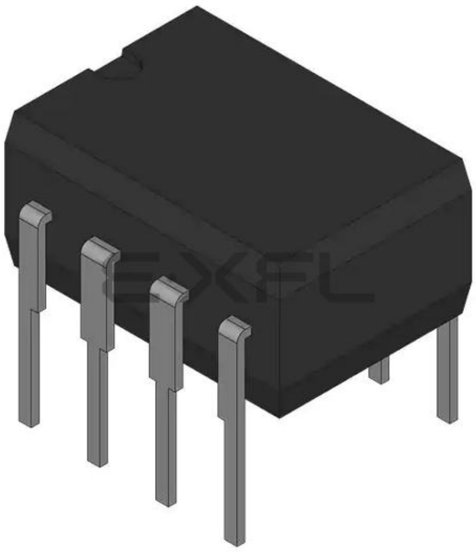

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	5
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc68hc908qt4cp

The following revision history table summarizes changes contained in this document. For your convenience, the page number designators have been linked to the appropriate location.

Revision History (Sheet 1 of 3)

Date	Revision Level	Description	Page Number(s)
September, 2002	N/A	Initial release	N/A
December, 2002	0.1	1.2 Features — Added 8-pin dual flat no lead (DFN) packages to features list.	19
		Figure 1-2. MCU Pin Assignments — Figure updated to include DFN packages.	21
		Figure 2-1. Memory Map — Clarified illegal address and unimplemented memory.	27
		Figure 2-2. Control, Status, and Data Registers — Corrected bit definitions for Port A Data Register (PTA) and Data Direction Register A (DDRA).	27
		Table 13-3. Interrupt Sources — Corrected vector addresses for keyboard interrupt and ADC conversion complete interrupt.	118
		Chapter 13 System Integration Module (SIM) — Removed reference to break status register as it is duplicated in break module.	113
		11.3.1 Internal Oscillator and 11.3.1.1 Internal Oscillator Trimming — Clarified oscillator trim option ordering information and what to expect with untrimmed device.	92
		Figure 11-5. Oscillator Trim Register (OSCTRIM) — Bit 1 designation corrected.	98
		Figure 15-13. Monitor Mode Circuit (Internal Clock, No High Voltage) — Diagram updated for clarity.	150
		Figure 12-1. I/O Port Register Summary — Corrected bit definitions for PTA7, DDRA7, and DDRA6.	99
		Figure 12-2. Port A Data Register (PTA) — Corrected bit definition for PTA7.	100
		Figure 12-3. Data Direction Register A (DDRA) — Corrected bit definitions for DDRA7 and DDRA6.	101
		Figure 12-6. Port B Data Register (PTB) — Corrected bit definition for PTB1	103
		Chapter 9 Keyboard Interrupt Module (KBI) — Section reworked after deletion of auto wakeup for clarity.	83
		Chapter 4 Auto Wakeup Module (AWU) — New section added for clarity.	49
		Figure 10-1. LVI Module Block Diagram — Corrected LVI stop representation.	87
		Chapter 16 Electrical Specifications — Extensive changes made to electrical specifications.	169
		17.5 8-Pin Dual Flat No Lead (DFN) Package (Case #1452) — Added case outline drawing for DFN package.	177
		Chapter 17 Ordering Information and Mechanical Specifications — Added ordering information for DFN package.	185
January, 2003	0.2	4.2 Features — Corrected third bulleted item.	49

Revision History (Sheet 2 of 3)

Date	Revision Level	Description	Page Number(s)
August, 2003	1.0	Reformatted to meet latest M68HC08 documentation standards	N/A
		Figure 1-1. Block Diagram — Diagram redrawn to include keyboard interrupt module and TCLK pin designator.	20
		Figure 1-2. MCU Pin Assignments — Added TCLK pin designator.	21
		Table 1-2. Pin Functions — Added TCLK pin description.	22
		Table 1-3. Function Priority in Shared Pins — Revised table for clarity and to add TCLK.	23
		Figure 2-1. Memory Map — Corrected names for the IRQ status and control register (INTSCR) bits 3–0.	26
		3.7.3 ADC Input Clock Register — Clarified bit description for the ADC clock prescaler bits.	47
		4.3 Functional Description — Updated periodic wakeup request values.	51
		Figure 6-1. COP Block Diagram — Reworked for clarity	59
		Chapter 8 External Interrupt (IRQ) — Corrected bit names for MODE, IRQF, ACK, and IMASK	77–79
		Chapter 14 Timer Interface Module (TIM) — Added TCLK function.	131–139
		15.3 Monitor Module (MON) — Updated with additional data.	147
		Chapter 16 Electrical Specifications — Updated with additional data.	169–173
October, 2003	2.0	Figure 2-2. Control, Status, and Data Registers — Deleted unimplemented areas from \$FFB0–\$FFBD and \$FFC2–\$FFCF as they are actually available. Also corrected \$FFBF designation from unimplemented to reserved.	27
		Figure 6-1. COP Block Diagram — Reworked for clarity	59
		6.3.2 STOP Instruction — Added subsection	60
		13.4.2 Active Resets from Internal Sources — Reworked notes for clarity.	111
		Table 13-2. Reset Recovery Timing — Replaced previous table with new information.	112
		Chapter 14 Timer Interface Module (TIM) — Updated with additional data.	131
		Figure 15-3. Break I/O Register Summary — Corrected bit designators for the BRKAR register	143
		15.3 Monitor Module (MON) — Clarified seventh bullet.	147
		Table 17-1. MC Order Numbers — Corrected temperature and package designators.	175
January, 2004	3.0	Figure 2-2. Control, Status, and Data Registers — Corrected reset state for the FLASH Block Protect Register at address location \$FFBE and the Internal Oscillator Trim Value at \$FFC0.	32
		Figure 2-5. FLASH Block Protect Register (FLBPR) — Restated reset state for clarity.	38

Revision History (Sheet 3 of 3)

Date	Revision Level	Description	Page Number(s)
November, 2004	4.0	Reformatted to meet current documentation standards	Throughout
		6.3.1 BUSCLKX4 — Clarified description of BUSCLKX4	58
		Chapter 7 Central Processor Unit (CPU) — In 7.7 Instruction Set Summary: Reworked definitions for STOP instruction Added WAIT instruction	 70 71
		13.8.1 SIM Reset Status Register — Clarified SRSR flag setting	117
		14.9.1 TIM Status and Control Register — Added information to TSTOP note	127
		16.8 5-V Oscillator Characteristics — Added values for deviation from trimmed inernal oscillator	155
		16.12 3-V Oscillator Characteristics — Added values for deviation from trimmed inernal oscillator	158
July, 2005	5.0	Figure 5-2. Configuration Register 1 (CONFIG1) — Clarified bit definitions for COPRS.	54
		Chapter 8 External Interrupt (IRQ) — Reworked for clarification.	73
		11.3.4 RC Oscillator — Improved RC oscillator wording.	93
		12.1 Introduction — Added note pertaining to non-bonded port pins.	97
		17.3 Package Dimensions — Updated package information.	165
March, 2010	6.0	Clarify internal oscillator trim register information.	26, 27, 31, 34, 35, 38, 91, 96

Chapter 10
Low-Voltage Inhibit (LVI)

Chapter 11
Oscillator Module (OSC)

- On-chip in-application programmable FLASH memory (with internal program/erase voltage generation)
  - MC68HC908QY4 and MC68HC908QT4 — 4096 bytes
  - MC68HC908QY2, MC68HC908QY1, MC68HC908QT2, and MC68HC908QT1 — 1536 bytes
- 128 bytes of on-chip random-access memory (RAM)
- 2-channel, 16-bit timer interface module (TIM)
- 4-channel, 8-bit analog-to-digital converter (ADC) on MC68HC908QY2, MC68HC908QY4, MC68HC908QT2, and MC68HC908QT4
- 5 or 13 bidirectional input/output (I/O) lines and one input only:
  - Six shared with keyboard interrupt function and ADC
  - Two shared with timer channels
  - One shared with external interrupt (IRQ)
  - Eight extra I/O lines on 16-pin package only
  - High current sink/source capability on all port pins
  - Selectable pullups on all ports, selectable on an individual bit basis
  - Three-state ability on all port pins
- 6-bit keyboard interrupt with wakeup feature (KBI)
- Low-voltage inhibit (LVI) module features:
  - Software selectable trip point in CONFIG register
- System protection features:
  - Computer operating properly (COP) watchdog
  - Low-voltage detection with reset
  - Illegal opcode detection with reset
  - Illegal address detection with reset
- External asynchronous interrupt pin with internal pullup ($\overline{IRQ}$) shared with general-purpose input pin
- Master asynchronous reset pin ($\overline{RST}$) shared with general-purpose input/output (I/O) pin
- Power-on reset
- Internal pullups on $\overline{IRQ}$ and $\overline{RST}$ to reduce external components
- Memory mapped I/O registers
- Power saving stop and wait modes
- MC68HC908QY4, MC68HC908QY2, and MC68HC908QY1 are available in these packages:
  - 16-pin plastic dual in-line package (PDIP)
  - 16-pin small outline integrated circuit (SOIC) package
  - 16-pin thin shrink small outline package (TSSOP)
- MC68HC908QT4, MC68HC908QT2, and MC68HC908QT1 are available in these packages:
  - 8-pin PDIP
  - 8-pin SOIC
  - 8-pin dual flat no lead (DFN) package

8. Wait for time, t_{PROG} (minimum 30 μs).
9. Repeat step 7 and 8 until all desired bytes within the row are programmed.
10. Clear the PGM bit[1].
11. Wait for time, t_{NVH} (minimum 5 μs).
12. Clear the HVEN bit.
13. After time, t_{RCV} (typical 1 μs), the memory can be accessed in read mode again.

NOTE

The COP register at location $FFFF should not be written between steps 5–12, when the HVEN bit is set. Since this register is located at a valid FLASH address, unpredictable behavior may occur if this location is written while HVEN is set.

This program sequence is repeated throughout the memory until all data is programmed.

NOTE

Programming and erasing of FLASH locations cannot be performed by code being executed from the FLASH memory. While these operations must be performed in the order shown, other unrelated operations may occur between the steps. Do not exceed t_{PROG} maximum, see 16.16 Memory Characteristics.

2.6.5 FLASH Protection

Due to the ability of the on-board charge pump to erase and program the FLASH memory in the target application, provision is made to protect blocks of memory from unintentional erase or program operations due to system malfunction. This protection is done by use of a FLASH block protect register (FLBPR). The FLBPR determines the range of the FLASH memory which is to be protected. The range of the protected area starts from a location defined by FLBPR and ends to the bottom of the FLASH memory ($FFFF). When the memory is protected, the HVEN bit cannot be set in either ERASE or PROGRAM operations.

NOTE

In performing a program or erase operation, the FLASH block protect register must be read after setting the PGM or ERASE bit and before asserting the HVEN bit.

When the FLBPR is programmed with all 0 s, the entire memory is protected from being programmed and erased. When all the bits are erased (all 1's), the entire memory is accessible for program and erase.

When bits within the FLBPR are programmed, they lock a block of memory. The address ranges are shown in 2.6.6 FLASH Block Protect Register. Once the FLBPR is programmed with a value other than $FF, any erase or program of the FLBPR or the protected block of FLASH memory is prohibited. Mass erase is disabled whenever any block is protected (FLBPR does not equal $FF). The FLBPR itself can be erased or programmed only with an external voltage, V_{TST}, present on the $\overline{IRQ}$ pin. This voltage also allows entry from reset into the monitor mode.

2. The time between each FLASH address change, or the time between the last FLASH address programmed to clearing PGM bit, must not exceed the maximum programming time, t_{PROG} maximum.

3.7.2 ADC Data Register

One 8-bit result register is provided. This register is updated each time an ADC conversion completes.

Address: $003E

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0
Write:								
Reset:	Indeterminate after reset							

= Unimplemented

Figure 3-4. ADC Data Register (ADR)

3.7.3 ADC Input Clock Register

This register selects the clock frequency for the ADC.

Address: $003F

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	ADIV2	ADIV1	ADIV0	0	0	0	0	0
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 3-5. ADC Input Clock Register (ADICLK)

ADIV2–ADIV0 — ADC Clock Prescaler Bits

ADIV2, ADIV1, and ADIV0 form a 3-bit field which selects the divide ratio used by the ADC to generate the internal ADC clock. Table 3-2 shows the available clock configurations. The ADC clock frequency should be set between $f_{ADIC(MIN)}$ and $f_{ADIC(MAX)}$. The analog input level should remain stable for the entire conversion time (maximum = 17 ADC clock cycles).

Table 3-2. ADC Clock Divide Ratio

ADIV2	ADIV1	ADIV0	ADC Clock Rate
0	0	0	Bus clock ÷ 1
0	0	1	Bus clock ÷ 2
0	1	0	Bus clock ÷ 4
0	1	1	Bus clock ÷ 8
1	X	X	Bus clock ÷ 16

X = don’t care

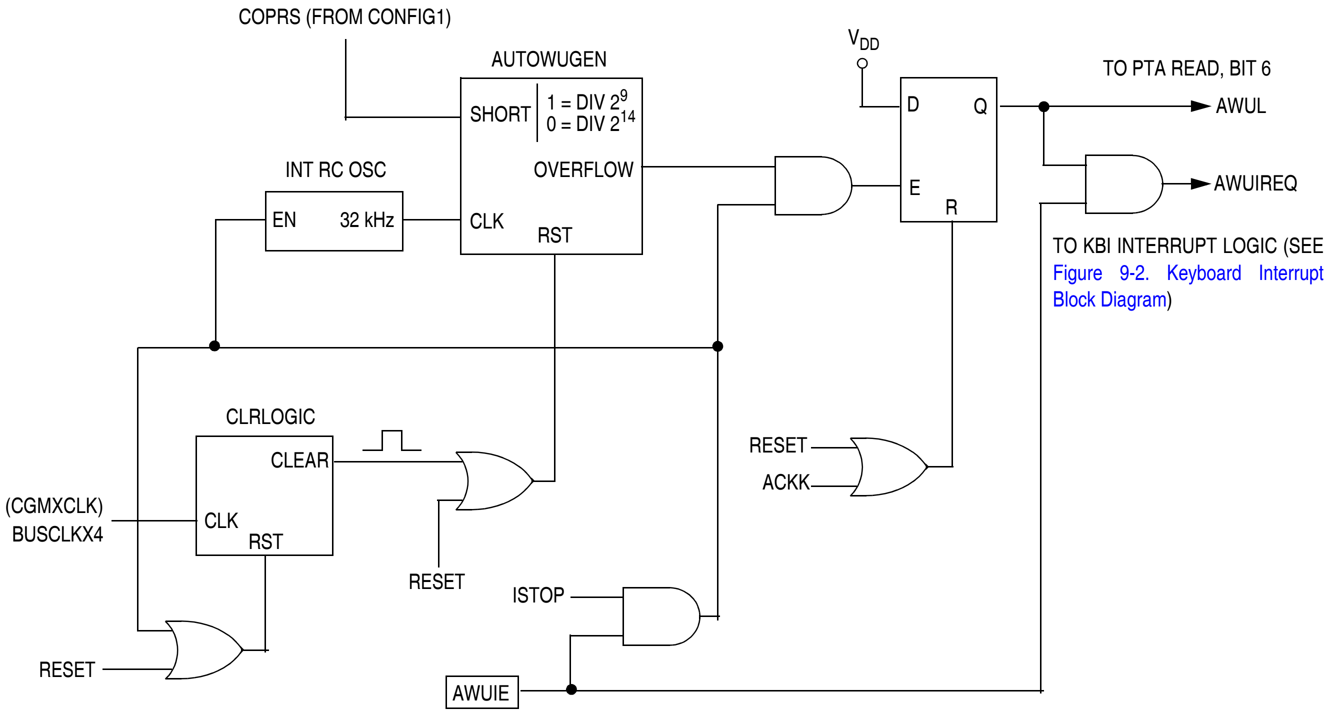


Figure 4-1. Auto Wakeup Interrupt Request Generation Logic

The auto wakeup RC oscillator is highly dependent on operating voltage and temperature. This feature is not recommended for use as a time-keeping function.

The wakeup request is latched to allow the interrupt source identification. The latched value, AWUL, can be read directly from the bit 6 position of PTA data register. This is a read-only bit which is occupying an empty bit position on PTA. No PTA associated registers, such as PTA6 data, PTA6 direction, and PTA6 pullup exist for this bit. The latch can be cleared by writing to the ACKK bit in the KBSCR register. Reset also clears the latch. AWUIE bit in KBI interrupt enable register (see Figure 4-1) has no effect on AWUL reading.

The AWU oscillator and counters are inactive in normal operating mode and become active only upon entering stop mode.

4.4 Wait Mode

The AWU module remains inactive in wait mode.

4.5 Stop Mode

When the AWU module is enabled (AWUIE = 1 in the keyboard interrupt enable register) it is activated automatically upon entering stop mode. Clearing the IMASKK bit in the keyboard status and control register enables keyboard interrupt requests to bring the MCU out of stop mode. The AWU counters start from ‘0’ each time stop mode is entered.

9.7.2 Keyboard Interrupt Enable Register

The port A keyboard interrupt enable register (KBIER) enables or disables each port A pin or auto wakeup to operate as a keyboard interrupt input.

Address: $001B

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	AWUIE	KBIE5	KBIE4	KBIE3	KBIE2	KBIE1	KBIE0
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 9-4. Keyboard Interrupt Enable Register (KBIER)

KBIE5–KBIE0 — Port A Keyboard Interrupt Enable Bits

Each of these read/write bits enables the corresponding keyboard interrupt pin on port A to latch interrupt requests. Reset clears the keyboard interrupt enable register.

1 = KBIx pin enabled as keyboard interrupt pin
0 = KBIx pin not enabled as keyboard interrupt pin

NOTE

AWUIE bit is not used in conjunction with the keyboard interrupt feature. To see a description of this bit, see Chapter 4 Auto Wakeup Module (AWU).

10.4 LVI Status Register

The LVI status register (LVISR) indicates if the V_{DD} voltage was detected below the V_{TRIPF} level while LVI resets have been disabled.

Address: $FE0C

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	LVIOUT	0	0	0	0	0	0	R
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented   R = Reserved

Figure 10-2. LVI Status Register (LVISR)

LVIOUT — LVI Output Bit

This read-only flag becomes set when the V_{DD} voltage falls below the V_{TRIPF} trip voltage and is cleared when V_{DD} voltage rises above V_{TRIPR}. The difference in these threshold levels results in a hysteresis that prevents oscillation into and out of reset (see Table 10-1). Reset clears the LVIOUT bit.

Table 10-1. LVIOUT Bit Indication

V_{DD}	LVIOUT
$V_{DD} > V_{TRIPR}$	0
$V_{DD} < V_{TRIPF}$	1
$V_{TRIPF} < V_{DD} < V_{TRIPR}$	Previous value

10.5 LVI Interrupts

The LVI module does not generate interrupt requests.

10.6 Low-Power Modes

The STOP and WAIT instructions put the MCU in low power-consumption standby modes.

10.6.1 Wait Mode

If enabled, the LVI module remains active in wait mode. If enabled to generate resets, the LVI module can generate a reset and bring the MCU out of wait mode.

10.6.2 Stop Mode

When the LVIPWRD bit in the configuration register is cleared and the LVISTOP bit in the configuration register is set, the LVI module remains active in stop mode. If enabled to generate resets, the LVI module can generate a reset and bring the MCU out of stop mode.

Chapter 11
Oscillator Module (OSC)

11.1 Introduction

The oscillator module is used to provide a stable clock source for the microcontroller system and bus. The oscillator module generates two output clocks, BUSCLKX2 and BUSCLKX4. The BUSCLKX4 clock is used by the system integration module (SIM) and the computer operating properly module (COP). The BUSCLKX2 clock is divided by two in the SIM to be used as the bus clock for the microcontroller. Therefore the bus frequency will be one fourth of the BUSCLKX4 frequency.

11.2 Features

The oscillator has these four clock source options available:

1. Internal oscillator: An internally generated, fixed frequency clock, trimmable to ±5%.This is the default option out of reset.
2. External oscillator: An external clock that can be driven directly into OSC1.
3. External RC: A built-in oscillator module (RC oscillator) that requires an external R connection only. The capacitor is internal to the chip.
4. External crystal: A built-in oscillator module (XTAL oscillator) that requires an external crystal or ceramic-resonator.

11.3 Functional Description

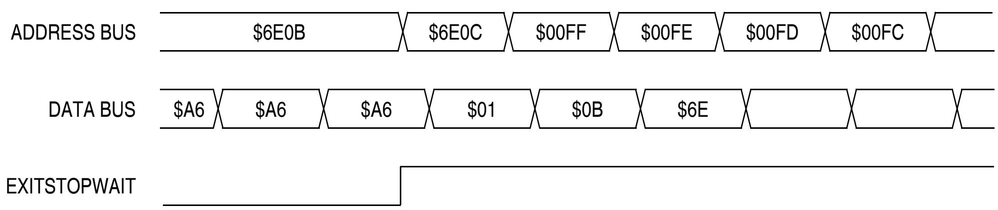
The oscillator contains these major subsystems:

- Internal oscillator circuit
- Internal or external clock switch control
- External clock circuit
- External crystal circuit
- External RC clock circuit

A module that is active during wait mode can wake up the CPU with an interrupt if the interrupt is enabled. Stacking for the interrupt begins one cycle after the WAIT instruction during which the interrupt occurred. In wait mode, the CPU clocks are inactive. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

Wait mode can also be exited by a reset (or break in emulation mode). A break interrupt during wait mode sets the SIM break stop/wait bit, SBSW, in the break status register (BSR). If the COP disable bit, COPD, in the configuration register is 0, then the computer operating properly module (COP) is enabled and remains active in wait mode.

Figure 13-15 and Figure 13-16 show the timing for wait recovery.



NOTE: EXITSTOPWAIT = $\overline{\text{RST}}$ pin OR CPU interrupt OR break interrupt

Figure 13-15. Wait Recovery from Interrupt

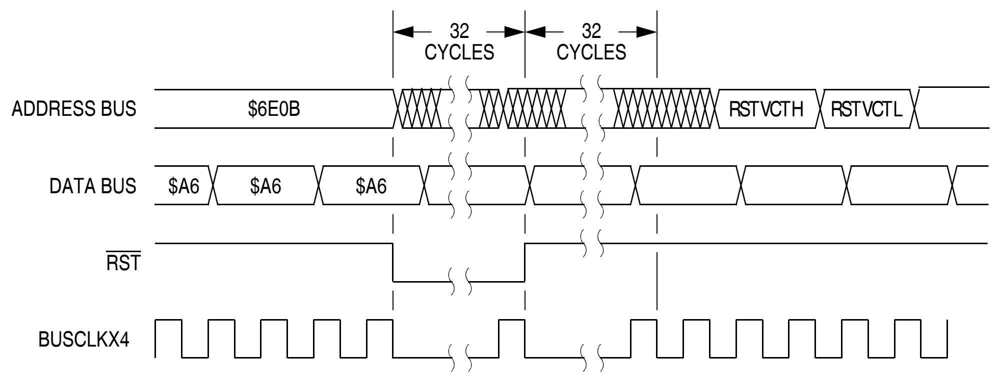


Figure 13-16. Wait Recovery from Internal Reset

13.7.2 Stop Mode

In stop mode, the SIM counter is reset and the system clocks are disabled. An interrupt request from a module can cause an exit from stop mode. Stacking for interrupts begins after the selected stop recovery time has elapsed. Reset or break also causes an exit from stop mode.

The SIM disables the oscillator signals (BUSCLKX2 and BUSCLKX4) in stop mode, stopping the CPU and peripherals. Stop recovery time is selectable using the SSREC bit in the configuration register 1 (CONFIG1). If SSREC is set, stop recovery is reduced from the normal delay of 4096 BUSCLKX4 cycles down to 32. This is ideal for the internal oscillator, RC oscillator, and external oscillator options which do not require long start-up times from stop mode.

NOTE

External crystal applications should use the full stop recovery time by clearing the SSREC bit.

control the output are the ones written to last. TSC0 controls and monitors the buffered output compare function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

NOTE

In buffered output compare operation, do not write new output compare values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered output compares.

14.4.4 Pulse Width Modulation (PWM)

By using the toggle-on-overflow feature with an output compare channel, the TIM can generate a PWM signal. The value in the TIM counter modulo registers determines the period of the PWM signal. The channel pin toggles when the counter reaches the value in the TIM counter modulo registers. The time between overflows is the period of the PWM signal

As Figure 14-3 shows, the output compare value in the TIM channel registers determines the pulse width of the PWM signal. The time between overflow and output compare is the pulse width. Program the TIM to clear the channel pin on output compare if the state of the PWM pulse is logic 1 (ELSxA = 0). Program the TIM to set the pin if the state of the PWM pulse is logic 0 (ELSxA = 1).

The value in the TIM counter modulo registers and the selected prescaler output determines the frequency of the PWM output The frequency of an 8-bit PWM signal is variable in 256 increments. Writing $00FF (255) to the TIM counter modulo registers produces a PWM period of 256 times the internal bus clock period if the prescaler select value is 000. See 14.9.1 TIM Status and Control Register.

The value in the TIM channel registers determines the pulse width of the PWM output. The pulse width of an 8-bit PWM signal is variable in 256 increments. Writing $0080 (128) to the TIM channel registers produces a duty cycle of 128/256 or 50%.

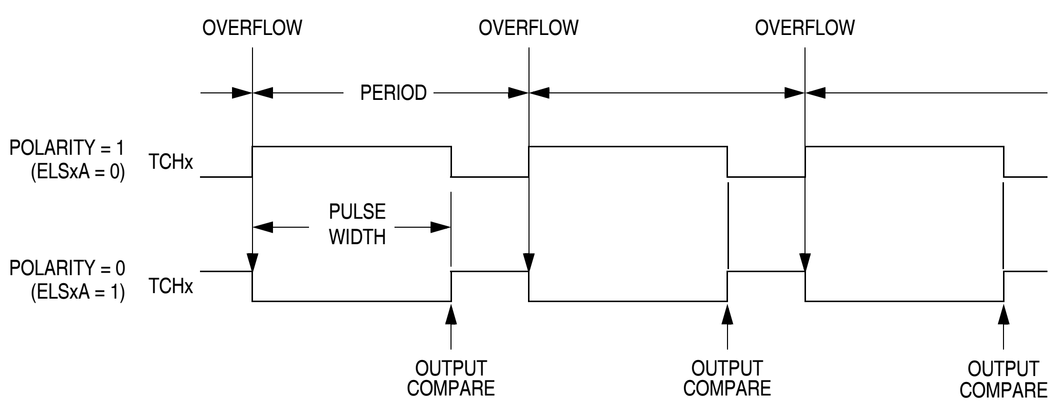


Figure 14-3. PWM Period and Pulse Width

Address: $0025 TSC0

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	TOV0	CH0MAX
Write:	0							
Reset:	0	0	0	0	0	0	0	0

Address: $0028 TSC1

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	CH1F	CH1IE	0	MS1A	ELS1B	ELS1A	TOV1	CH1MAX
Write:	0							
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 14-7. TIM Channel Status and Control Registers (TSC0:TSC1)

CHxF — Channel x Flag Bit

When channel x is an input capture channel, this read/write bit is set when an active edge occurs on the channel x pin. When channel x is an output compare channel, CHxF is set when the value in the TIM counter registers matches the value in the TIM channel x registers.

Clear CHxF by reading the TIM channel x status and control register with CHxF set and then writing a 0 to CHxF. If another interrupt request occurs before the clearing sequence is complete, then writing a 0 to CHxF has no effect. Therefore, an interrupt request cannot be lost due to inadvertent clearing of CHxF.

Reset clears the CHxF bit. Writing a 1 to CHxF has no effect.

1 = Input capture or output compare on channel x
0 = No input capture or output compare on channel x

CHxIE — Channel x Interrupt Enable Bit

This read/write bit enables TIM CPU interrupt service requests on channel x. Reset clears the CHxIE bit.

1 = Channel x CPU interrupt requests enabled
0 = Channel x CPU interrupt requests disabled

MSxB — Mode Select Bit B

This read/write bit selects buffered output compare/PWM operation. MSxB exists only in the TIM channel 0 status and control register.

Setting MS0B disables the channel 1 status and control register and reverts TCH1 to general-purpose I/O.

Reset clears the MSxB bit.

1 = Buffered output compare/PWM operation enabled
0 = Buffered output compare/PWM operation disabled

MSxA — Mode Select Bit A

When ELSxB:A $\neq$ 00, this read/write bit selects either input capture operation or unbuffered output compare/PWM operation. See Table 14-3.

1 = Unbuffered output compare/PWM operation
0 = Input capture operation

15.2.2.1 Break Status and Control Register

The break status and control register (BRKSCR) contains break module enable and status bits.

Address: $FE0B

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	BRKE	BRKA	0	0	0	0	0	0
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 15-3. Break Status and Control Register (BRKSCR)

BRKE — Break Enable Bit

This read/write bit enables breaks on break address register matches. Clear BRKE by writing a 0 to bit 7. Reset clears the BRKE bit.

1 = Breaks enabled on 16-bit address match
0 = Breaks disabled

BRKA — Break Active Bit

This read/write status and control bit is set when a break address match occurs. Writing a 1 to BRKA generates a break interrupt. Clear BRKA by writing a 0 to it before exiting the break routine. Reset clears the BRKA bit.

1 = Break address match
0 = No break address match

15.2.2.2 Break Address Registers

The break address registers (BRKH and BRKL) contain the high and low bytes of the desired breakpoint address. Reset clears the break address registers.

Address: $FE09

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
Reset:	0	0	0	0	0	0	0	0

Figure 15-4. Break Address Register High (BRKH)

Address: $FE0A

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Reset:	0	0	0	0	0	0	0	0

Figure 15-5. Break Address Register Low (BRKL)

Chapter 16
Electrical Specifications

16.1 Introduction

This section contains electrical and timing specifications.

16.2 Absolute Maximum Ratings

Maximum ratings are the extreme limits to which the microcontroller unit (MCU) can be exposed without permanently damaging it.

NOTE

This device is not guaranteed to operate properly at the maximum ratings. Refer to 16.5 5-V DC Electrical Characteristics and 16.9 3-V DC Electrical Characteristics for guaranteed operating conditions.

Characteristic[1]	Symbol	Value	Unit
Supply voltage	V_{DD}	–0.3 to +6.0	V
Input voltage	V_{IN}	V_{SS} –0.3 to V_{DD} +0.3	V
Mode entry voltage, $\overline{IRQ}$ pin	V_{TST}	V_{SS} –0.3 to +9.1	V
Maximum current per pin excluding PTA0–PTA5, V_{DD}, and V_{SS}	I	±15	mA
Maximum current for pins PTA0–PTA5	I_{PTA0}—I_{PTA5}	±25	mA
Storage temperature	T_{STG}	–55 to +150	°C
Maximum current out of V_{SS}	I_{MVSS}	100	mA
Maximum current into V_{DD}	I_{MVDD}	100	mA

1. Voltages references to V_{SS}.

NOTE

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum-rated voltages to this high-impedance circuit. For proper operation, it is recommended that V_{IN} and V_{OUT} be constrained to the range $V_{SS} \leq (V_{IN}$ or $V_{OUT}) \leq V_{DD}$. Reliability of operation is enhanced if unused inputs are connected to an appropriate logic voltage level (for example, either V_{SS} or V_{DD}.)

16.6 Typical 5-V Output Drive Characteristics

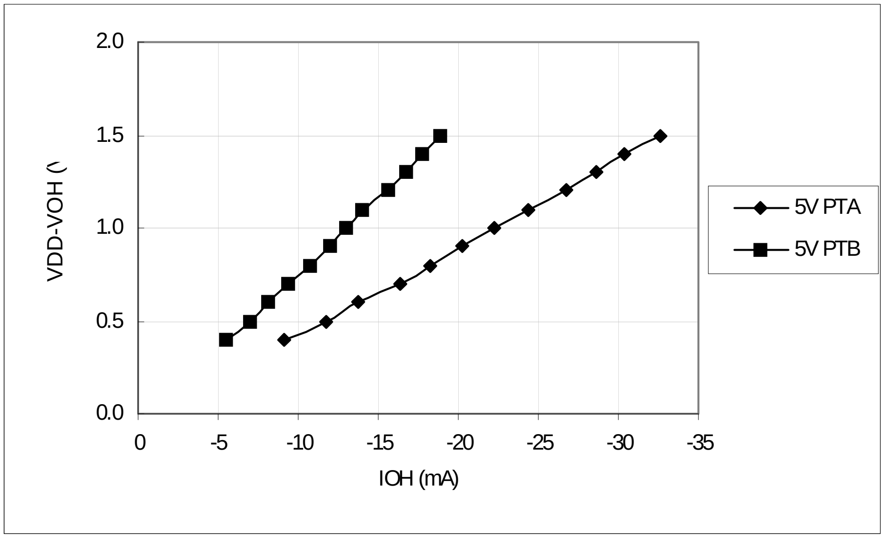


Figure 16-1. Typical 5-Volt Output High Voltage versus Output High Current (25•C)

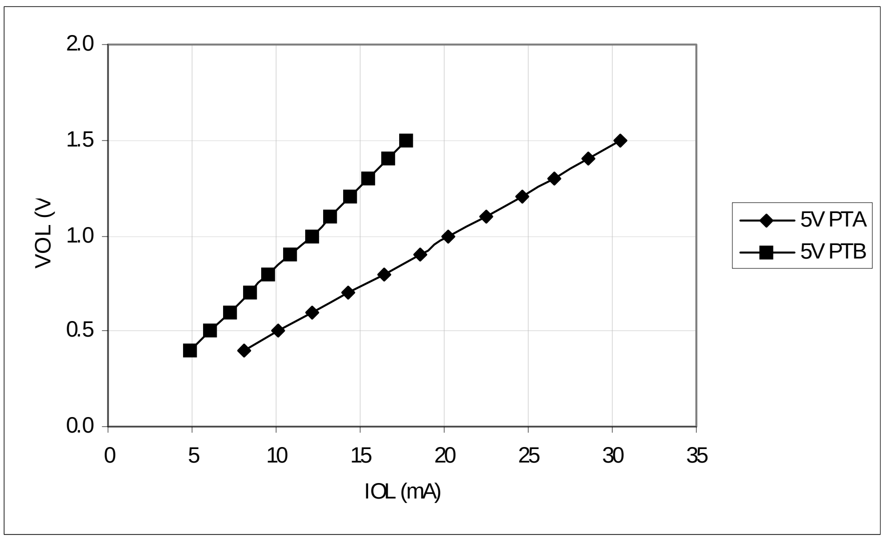


Figure 16-2. Typical 5-Volt Output Low Voltage versus Output Low Current (25•C)

16.9 3-V DC Electrical Characteristics

Characteristic[1]	Symbol	Min	Typ[2]	Max	Unit
Output high voltage I_{Load} = –0.6 mA, all I/O pins I_{Load} = –4.0 mA, all I/O pins I_{Load} = –10.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OH}	V_{DD}–0.3 V_{DD}–1.0 V_{DD}–0.8	— — —	— — —	V
Maximum combined I_{OH} (all I/O pins)	I_{OHT}	—	—	50	mA
Output low voltage I_{Load} = 0.5 mA, all I/O pins I_{Load} = 6.0 mA, all I/O pins I_{Load} = 10.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OL}	— — —	— — —	0.3 1.0 0.8	V
Maximum combined I_{OL} (all I/O pins)	I_{OLT}	—	—	50	mA
Input high voltage PTA0–PTA5, PTB0–PTB7	V_{IH}	0.7 x V_{DD}	—	V_{DD}	V
Input low voltage PTA0–PTA5, PTB0–PTB7	V_{IL}	V_{SS}	—	0.3 x V_{DD}	V
Input hysteresis	V_{HYS}	0.06 x V_{DD}	—	—	V
DC injection current, all ports	I_{INJ}	–2	—	+2	mA
Total dc current injection (sum of all I/O)	I_{INJTOT}	–25	—	+25	mA
Ports Hi-Z leakage current	I_{IL}	–1	±0.1	+1	µA
Capacitance Ports (as input) Ports (as input)	C_{IN} C_{OUT}	— —	— —	12 8	pF
POR rearm voltage[3]	V_{POR}	0	—	100	mV
POR rise time ramp rate[4]	R_{POR}	0.035	—	—	V/ms
Monitor mode entry voltage	V_{TST}	V_{DD} + 2.5	—	V_{DD} + 4.0	V
Pullup resistors[5] PTA0–PTA5, PTB0–PTB7	R_{PU}	16	26	36	kΩ
Low-voltage inhibit reset, trip falling voltage	V_{TRIPF}	2.40	2.55	2.70	V
Low-voltage inhibit reset, trip rising voltage	V_{TRIPR}	2.50	2.65	2.80	V
Low-voltage inhibit reset/recover hysteresis	V_{HYS}	—	60	—	mV

1. V_{DD} = 2.7 to 3.3 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25•C only.
3. Maximum is highest voltage that POR is guaranteed.
4. If minimum V_{DD} is not reached before the internal POR reset is released, the LVI will hold the part in reset until minimum V_{DD} is reached.
5. R_{PU} are measured at V_{DD} = 3.0 V

Chapter 17
Ordering Information and Mechanical Specifications

17.1 Introduction

This section contains order numbers for the MC68HC908QY1, MC68HC908QY2, MC68HC908QY4, MC68HC908QT1, MC68HC908QT2, and MC69HC908QT4. Dimensions are given for:

- 8-pin plastic dual in-line package (PDIP)
- 8-pin small outline integrated circuit (SOIC) package
- 8-pin dual flat no lead (DFN) package
- 16-pin PDIP
- 16-pin SOIC
- 16-pin thin shrink small outline package (TSSOP)

17.2 MC Order Numbers

Table 17-1. MC Order Numbers

MC Order Number	ADC	FLASH Memory	Package
MC908QY1	—	1536 bytes	16-pins PDIP, SOIC, and TSSOP
MC908QY2	Yes	1536 bytes	
MC908QY4	Yes	4096 bytes	
MC908QT1	—	1536 bytes	8-pins PDIP, SOIC, and DFN
MC908QT2	Yes	1536 bytes	
MC908QT4	Yes	4096 bytes	

Temperature and package designators:
C = –40•C to +85•C
V = –40•C to +105•C
M = –40•C to +125•C
P = Plastic dual in-line package (PDIP)
DW = Small outline integrated circuit package (SOIC)
DT = Thin shrink small outline package (TSSOP)
FQ = Dual flat no lead (DFN)

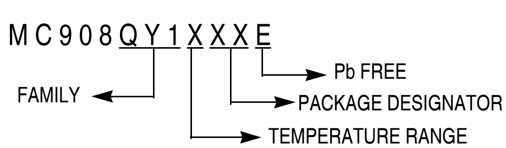


Figure 17-1. Device Numbering System

17.3 Package Dimensions

Refer to the following pages for detailed package dimensions.